

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V}$

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

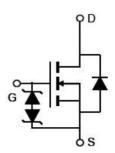
Features

- Optimized body diode reverse recovery performance
- ●Low on-resistance and low conduction losses
- Small package
- ●Ultra Low Gate Charge cause lower driving requirements
- ●100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge

V _{DS min@Tjmax}	710	V
R _{DS(ON)TYP}	230	mΩ
ID	14.5	Α
Qg	22	nC



Schematic diagram

Package Marking And Ordering Information

Device	Device Package	Marking
NCE65N260K	TO-252-2L	NCE65N260K



TO-252

Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (VGS=0V)	VDS	650	V
Gate-Source Voltage (VDS=0V) AC (f>1 Hz)	Vgs	±30	V
Gate-Source Voltage (VDS=0V) DC	Vgs	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	14.5	A
Continuous Drain Current at Tc=100°C	I _{D (DC)}	10.15	А
Pulsed drain current (Note 1)	I _{DM (pluse)}	43.5	А
Maximum Power Dissipation(Tc=25°C)	P _D	142	W
Derate above 25°C		0.94	W/°C
Avalanche current ^(Note 2)	I _{AS}	3.5	A
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55+175	°C

^{*} limited by maximum junction temperature



Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	1.05	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	<u>'</u>		•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	650			V
Zero Gate Voltage Drain Current(Tc=25°C)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			100	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±200	nA
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	3	3.5	4	٧
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =7A		230	260	mΩ
Dynamic Characteristics			•			
Input Capacitance	C _{lss}	V 50VV 0V		1104		pF
Output Capacitance	Coss	V_{DS} =50V, V_{GS} =0V,		40		pF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		3		pF
Total Gate Charge	Qg			22		nC
Gate-Source Charge	Q _{gs}	V_{DS} =480 V , I_{D} =7 A ,		7		nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V		5.5		nC
Gate plateau voltage	Vgp			5.5		V
Intrinsic gate resistance	R _G	f = 1 MHz open drain		18		Ω
Switching times			•			
Turn-on Delay Time	t _{d(on)}			11		nS
Turn-on Rise Time	t _r	V_{DD} =480 V , I_{D} =7 A ,		9		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=1.7\Omega, V_{GS}=10V$		57		nS
Turn-Off Fall Time	t _f			10		nS
Source- Drain Diode Characteristics			•			
Source-drain current(Body Diode)	I _{SD}	T 0500			14.5	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	T _C =25°C			43.5	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =14.5A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	t _{rr}	T:_05°C ! 7A		240		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =7A,		2.0		uC
Peak Reverse Recovery Current	I _{rrm}	di/dt=100A/μs		17		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

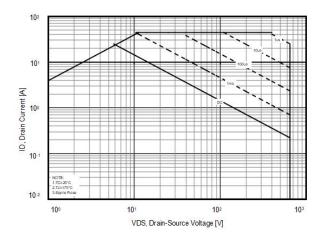


Figure 3. Transfer characteristics

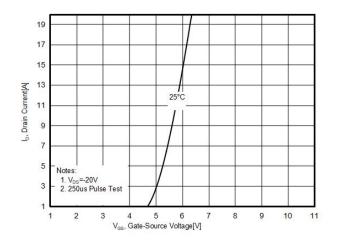


Figure 5. R_{DS(ON)} vs Junction Temperature

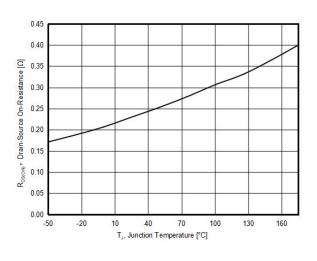


Figure 2. Capacitance

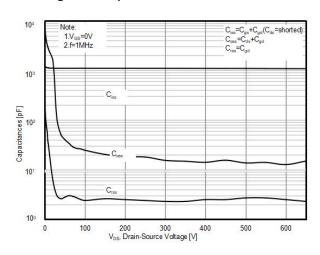


Figure 4. Output characteristics

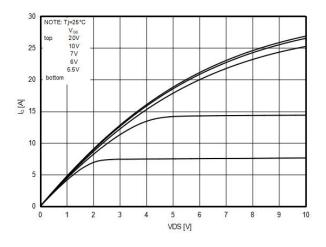


Figure 6. BV_{DSS} vs Junction Temperature

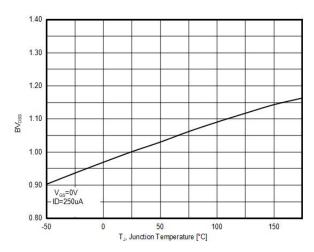




Figure 7. Maximum I_D vs Junction Temperature

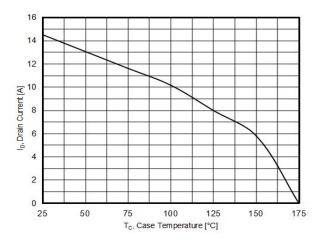


Figure 9. Static drain-source on resistance

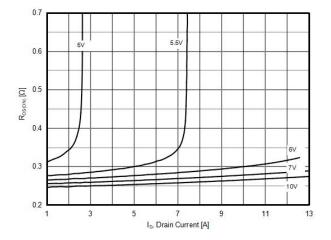


Figure 8. Gate charge waveforms

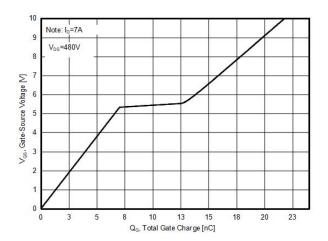
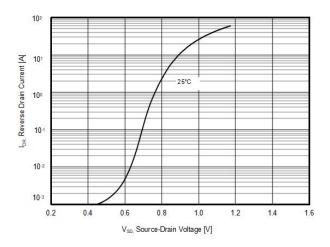


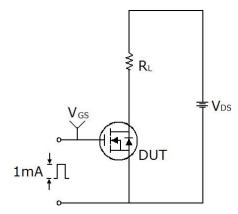
Figure 10. Source-Drain Diode Forward Voltag

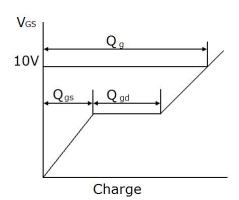




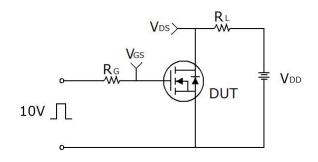
Test circuit

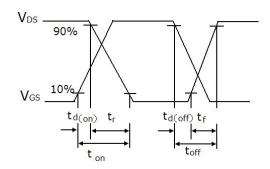
1) Gate charge test circuit & Waveform



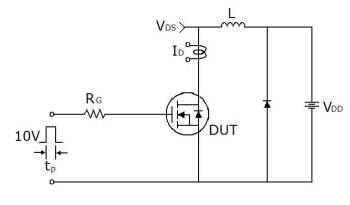


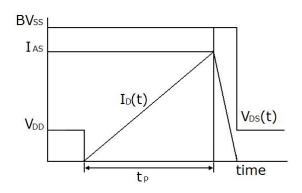
2) Switch Time Test Circuit:





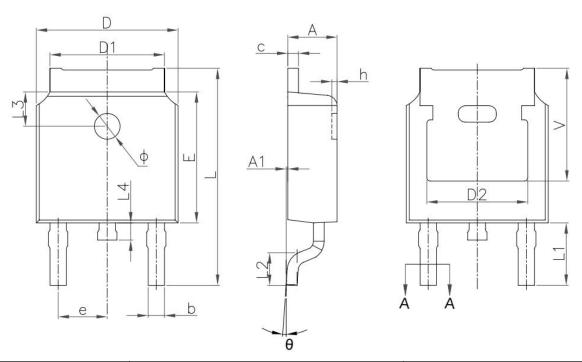
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-252-E Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min.	Max.	Min.	Max.		
Α	2.20	2.40	0.087	0.094		
A1	0.00	0.13	0.000	0.005		
b	0.66	0.86	0.026	0.033		
b1	0.73	0.79	0.029	0.031		
С	0.46	0.58	0.018	0.023		
c1	0.50	0.52	0.020	0.020		
D	6.50	6.70	0.256	0.264		
D1	5.10	5.46	0.201	0.215		
D2	4.83	4.83 REF		0.19REF		
E	6.00	6.20	0.236	0.244		
е	2.19	2.39	0.086	0.094		
L	9.80	10.40	0.386	0.409		
L1	2.90	2.90 REF		0.11REF		
L2	1.40	1.70	0.055			
L3	1.60	1.60 REF		REF		
L4	0.60	1.00	0.024	0.039		
Ф	1.10	1.30	0.043	0.051		
θ	0°	8°	0°	8°		
h	0.00	0.30	0.000	0.012		



ATTENTION:

- Any and all NCE products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE representative nearest you before using any NCE products described or contained herein in such applications.
- NCE assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE products described or contained herein.
- Specifications of any and all NCE products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE Power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE Power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE product that you intend to use.
- This catalog provides information as of Mar. 2010. Specifications and information herein are subject to change without notice.